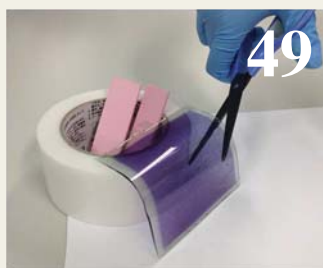


Photo 1: Development of power inductors for automotive ECUs that withstand 150°C has become active. (page 12)



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